


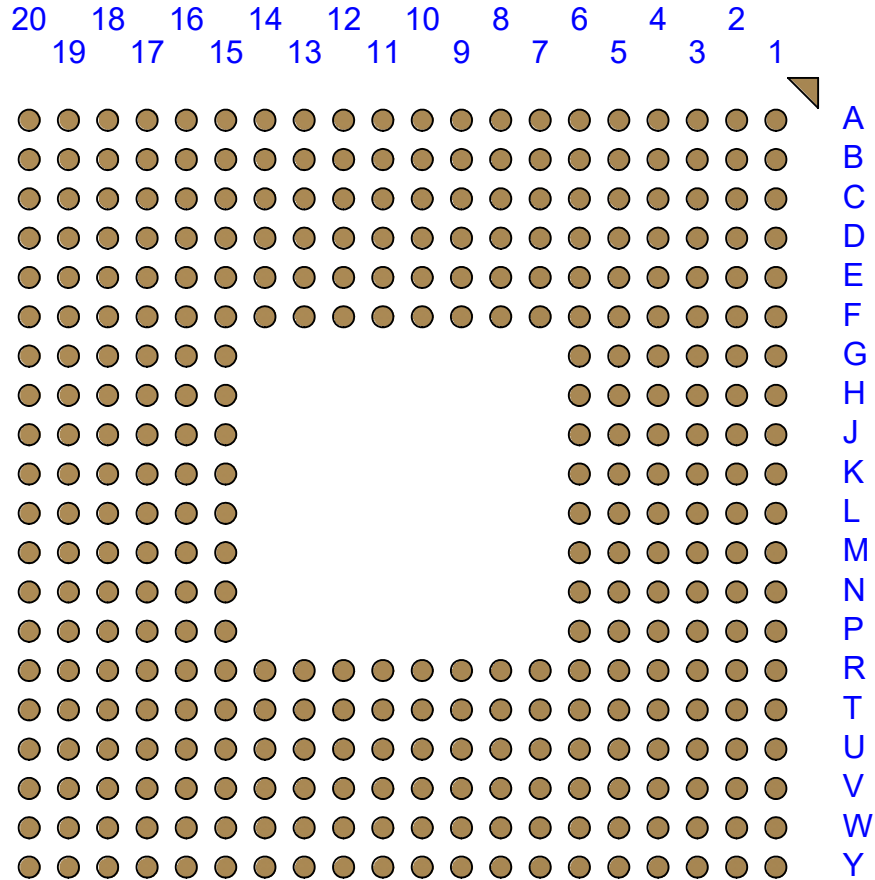
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.35mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.33mm.
- 5) PAD Cu DIAMETER: 0.457mm.
- 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
- 7) DUMMY DIE IS OPTIONAL.
- 8) BALL PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

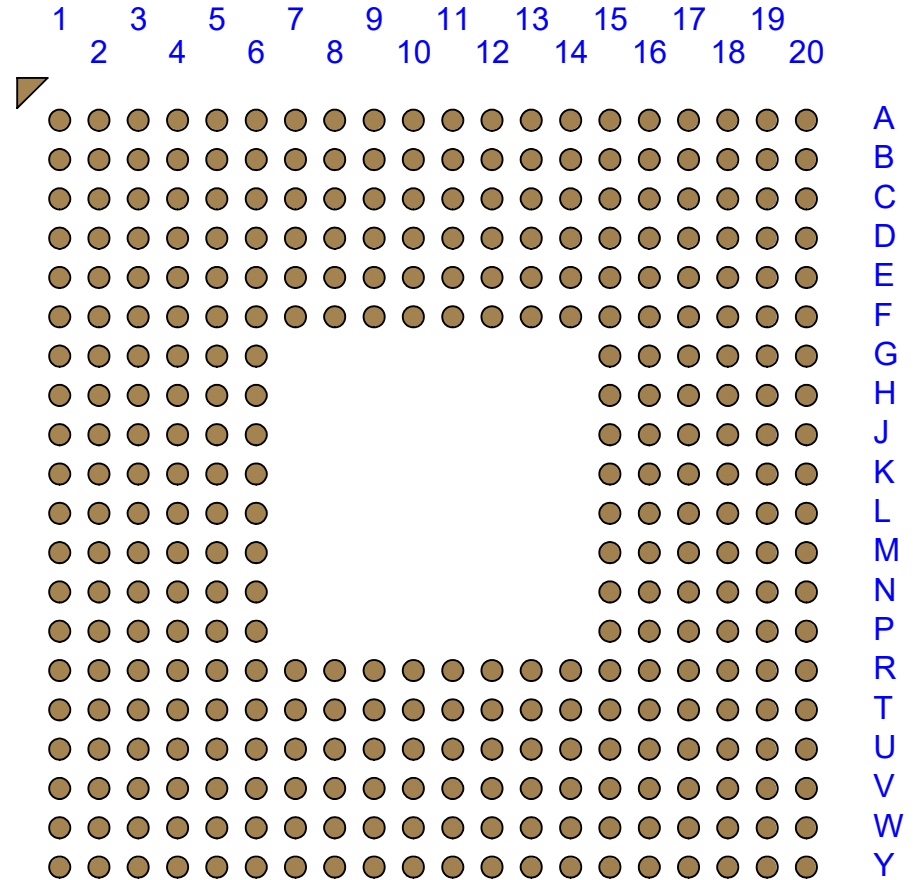
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA336T.65C-20X20-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA336T.65-20X20-D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE				
DRAW T. Au	7/16/2021				
ENG M. Hart	7/16/2021	TITLE		BGA336T.65C-20x20-D	
MFG				DUMMY BGA	
QA		SCALE	SIZE	DRAWING NO.	REV
CUST		5:1	A	165054	A
REVISED		DO NOT SCALE DRAWING			SHEET 1 OF 3

**BALL VIEW**



**BOTTOM SIDE  
(TOP X-RAY VIEW)**



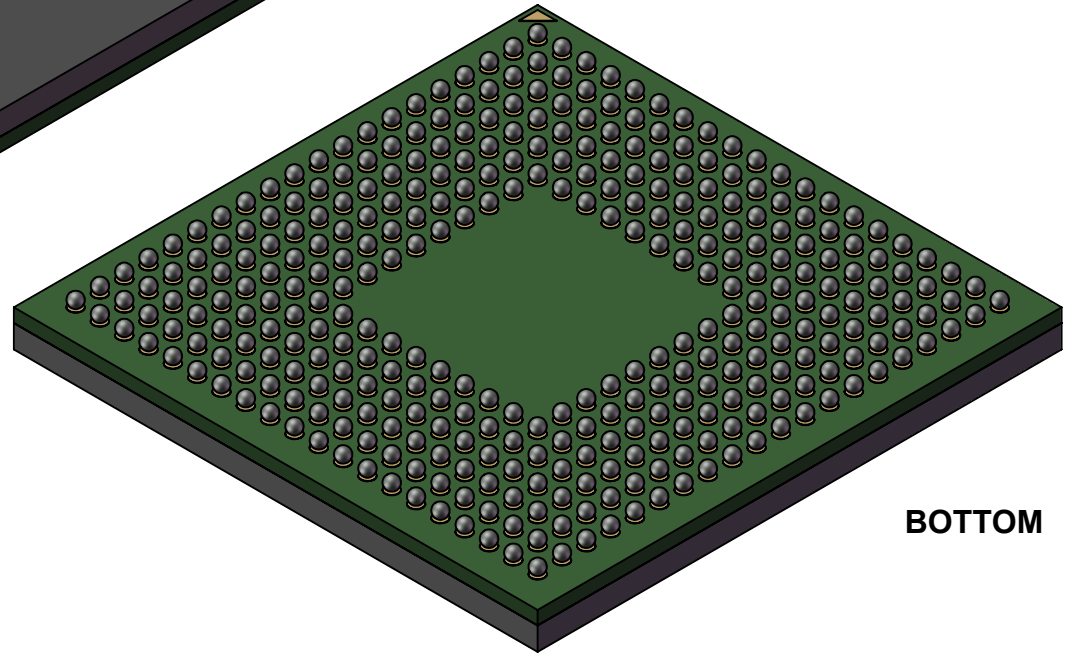
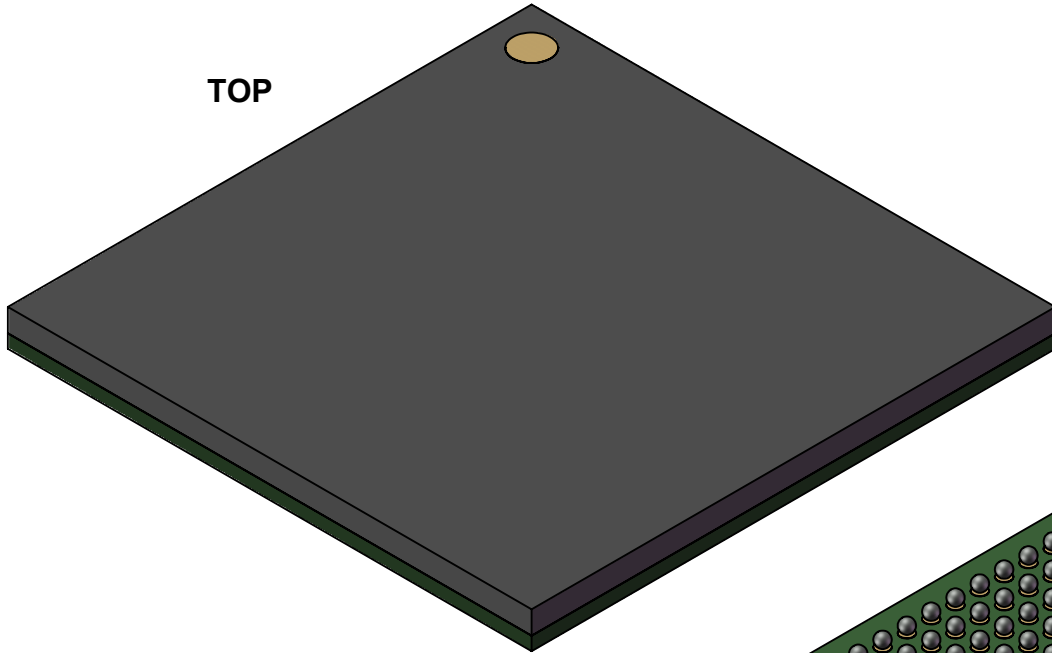
**Notes:**

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.457mm (18mil).
- 3) PCB TRACING LINE WIDTH 0.152mm (6mil).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.33mm (13mil).

<b>TopLine</b> ®			
TITLE		BGA336T.65C-20x20-D DUMMY BGA	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	165054	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

# MODEL

TOP



BOTTOM

<b>TopLine</b> <sup>®</sup>			
TITLE    BGA336T.65C-20x20-D DUMMY BGA			
SCALE 7:1	SIZE A	DRAWING NO. 165054	REV A
DO NOT SCALE DRAWING			SHEET 3 OF 3